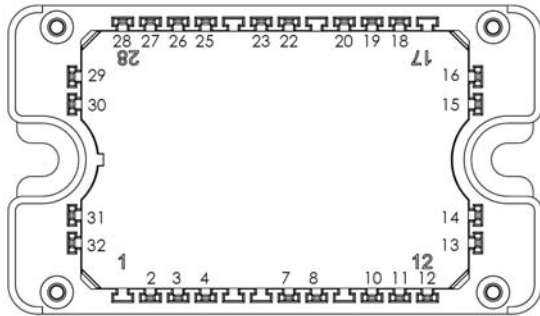
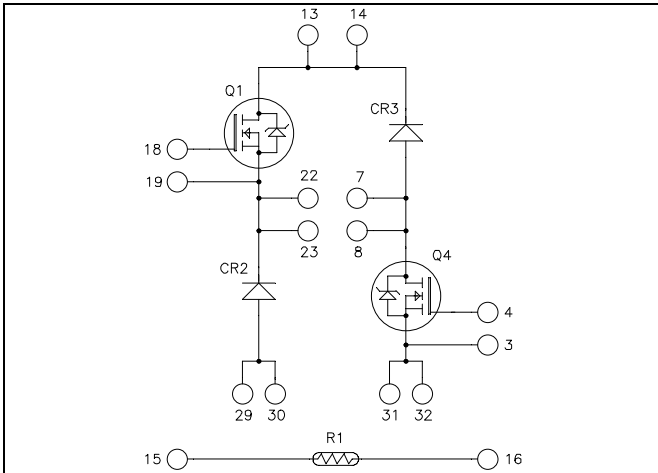


*Asymmetrical Bridge
Super Junction MOSFET
Power Module*

V_{DSS} = 600V
R_{DSon} = 24mΩ max @ T_j = 25°C
I_D = 95A @ T_c = 25°C



All multiple inputs and outputs must be shorted together
 Example: 13/14 ; 29/30 ; 22/23...

Application

- Welding converters
- Switched Mode Power Supplies
- Switched Reluctance Motor Drives

Features

- **Super junction MOSFET**
 - Ultra low R_{DSon}
 - Low Miller capacitance
 - Ultra low gate charge
 - Avalanche energy rated
 - Very rugged
- Kelvin source for easy drive
- Very low stray inductance
- Internal thermistor for temperature monitoring

Benefits

- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS compliant

All ratings @ T_j = 25°C unless otherwise specified

Absolute maximum ratings (per super junction MOSFET)

Symbol	Parameter	Max ratings	Unit
V _{DSS}	Drain - Source Voltage	600	V
I _D	Continuous Drain Current	T _c = 25°C	95
		T _c = 80°C	70
I _{DM}	Pulsed Drain current	260	A
V _{GS}	Gate - Source Voltage	±20	V
R _{DSon}	Drain - Source ON Resistance	24	mΩ
P _D	Power Dissipation	T _c = 25°C	462
I _{AR}	Avalanche current (repetitive and non repetitive)	15	A
E _{AR}	Repetitive Avalanche Energy	3	mJ
E _{AS}	Single Pulse Avalanche Energy	1900	

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

Electrical Characteristics (per super junction MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
I _{DSS}	Zero Gate Voltage Drain Current	V _{GS} = 0V, V _{DS} = 600V			350	μA
R _{DS(on)}	Drain – Source on Resistance	V _{GS} = 10V, I _D = 47.5A			24	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 5mA	2.1	3	3.9	V
I _{GSS}	Gate – Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0V			200	nA

Dynamic Characteristics (per super junction MOSFET)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
C _{iss}	Input Capacitance	V _{GS} = 0V ; V _{DS} = 25V f = 1MHz		14.4		nF
C _{oss}	Output Capacitance			17		
Q _g	Total gate Charge	V _{GS} = 10V V _{Bus} = 300V I _D = 95A		300		nC
Q _{gs}	Gate – Source Charge			68		
Q _{gd}	Gate – Drain Charge			102		
T _{d(on)}	Turn-on Delay Time	Inductive Switching (125°C) V _{GS} = 10V V _{Bus} = 400V I _D = 95A R _G = 2.5Ω		21		ns
T _r	Rise Time			30		
T _{d(off)}	Turn-off Delay Time			100		
T _f	Fall Time			45		
E _{on}	Turn-on Switching Energy	Inductive switching @ 25°C V _{GS} = 10V ; V _{Bus} = 400V I _D = 95A ; R _G = 2.5Ω		1350		μJ
E _{off}	Turn-off Switching Energy			1040		
E _{on}	Turn-on Switching Energy	Inductive switching @ 125°C V _{GS} = 10V ; V _{Bus} = 400V I _D = 95A ; R _G = 2.5Ω		2200		μJ
E _{off}	Turn-off Switching Energy			1270		
R _{thJC}	Junction to Case Thermal Resistance				0.27	°C/W

Diode ratings and characteristics (per diode)

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
V _{RRM}	Peak Repetitive Reverse Voltage				600	V
I _{RM}	Reverse Leakage Current	V _R = 600V			25	μA
I _F	DC Forward Current	T _c = 80°C		60		A
V _F	Diode Forward Voltage	I _F = 60A		1.7	2.3	V
		I _F = 120A		2		
		I _F = 60A T _j = 125°C		1.4		
t _{rr}	Reverse Recovery Time	I _F = 60A V _R = 400V	T _j = 25°C	70		ns
			T _j = 125°C	140		
Q _{rr}	Reverse Recovery Charge	di/dt = 200A/μs	T _j = 25°C	100		nC
			T _j = 125°C	690		
R _{thJC}	Junction to Case Thermal Resistance				0.85	°C/W

Thermal and package characteristics

Symbol	Characteristic	Min	Max	Unit		
V _{ISOL}	RMS Isolation Voltage, any terminal to case t=1 min, 50/60Hz	4000		V		
T _J	Operating junction temperature range	-40	150	°C		
T _{JOP}	Recommended junction temperature under switching conditions	-40	T _{Jmax} -25			
T _{STG}	Storage Temperature Range	-40	125			
T _C	Operating Case Temperature	-40	125			
Torque	Mounting torque	To heatsink	M4	2	3	N.m
Wt	Package Weight				110	g

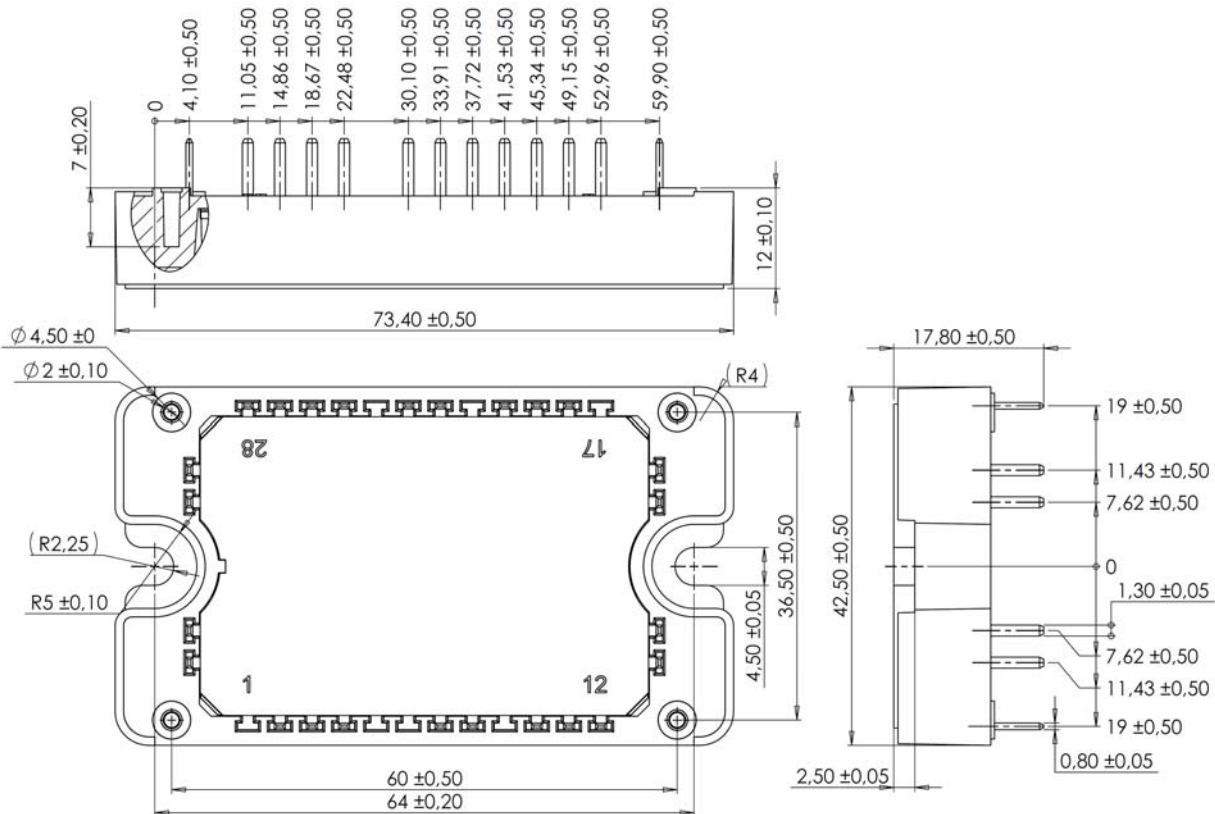
Temperature sensor NTC (see application note APT0406 on www.microsemi.com for more information).

Symbol	Characteristic	Min	Typ	Max	Unit
R ₂₅	Resistance @ 25°C		50		kΩ
ΔR ₂₅ /R ₂₅			5		%
B _{25/85}	T ₂₅ = 298.15 K		3952		K
ΔB/B	T _C = 100°C		4		%

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

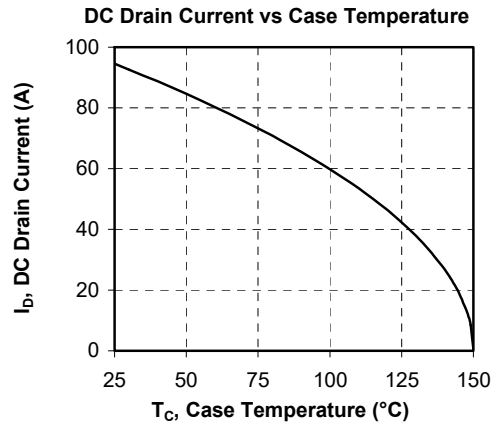
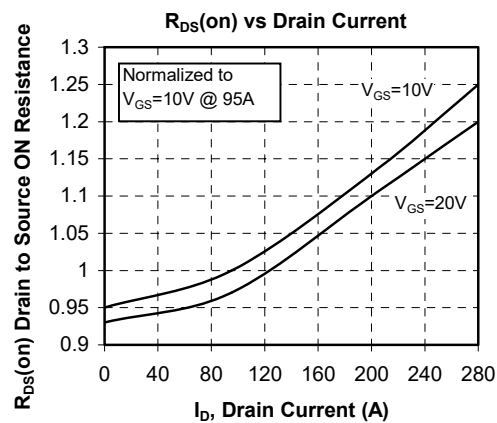
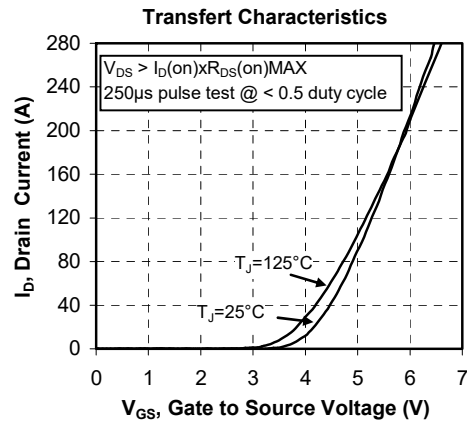
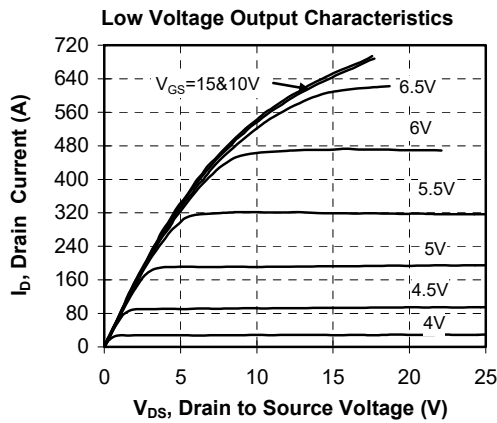
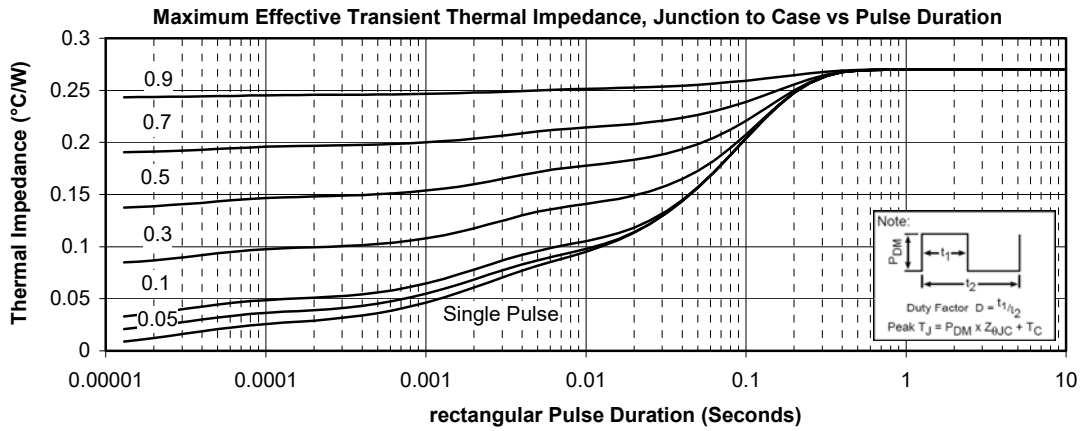
T: Thermistor temperature
 R_T: Thermistor value at T

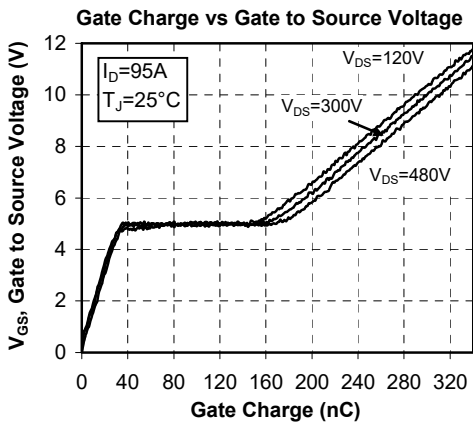
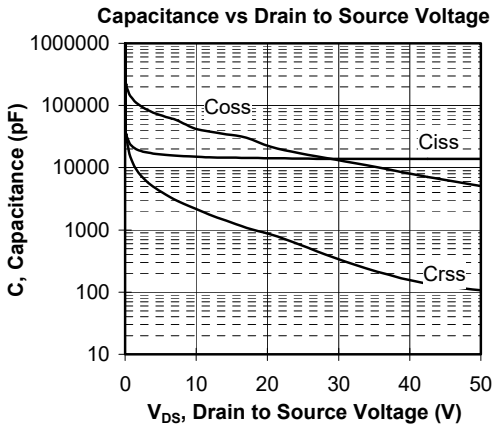
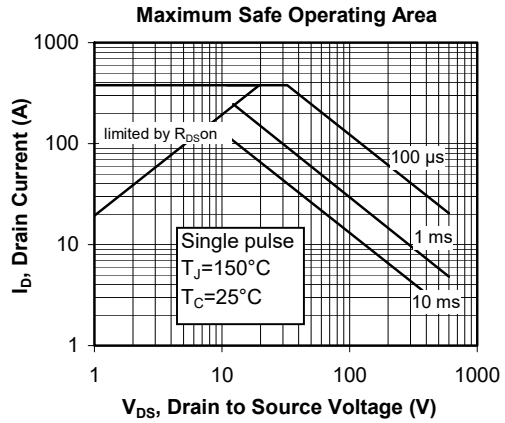
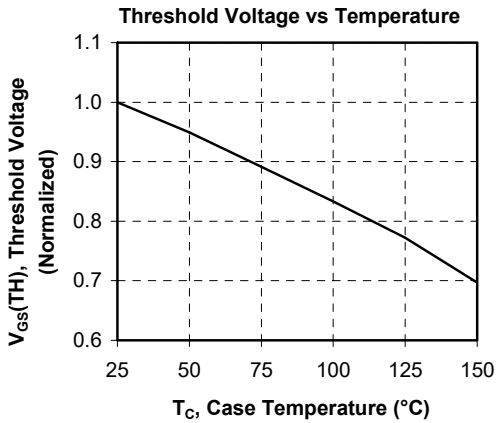
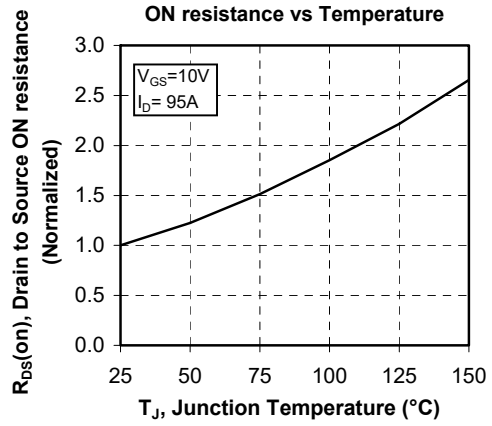
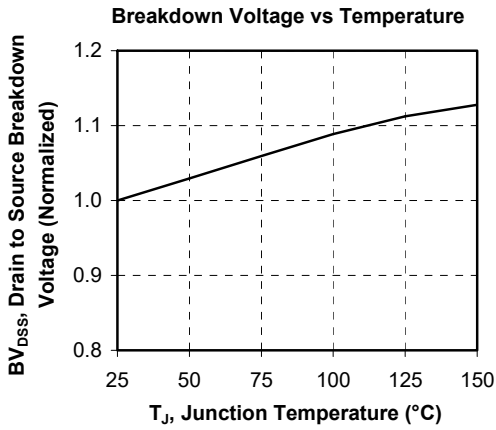
Package outline (dimensions in mm)

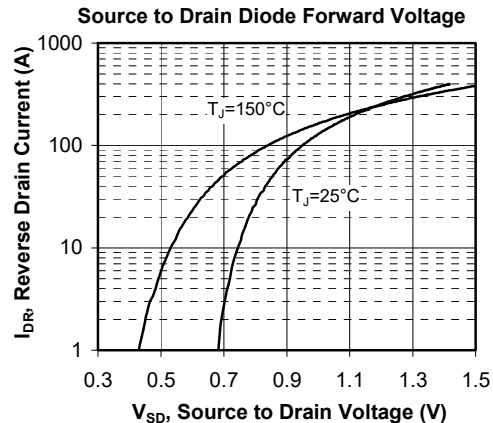
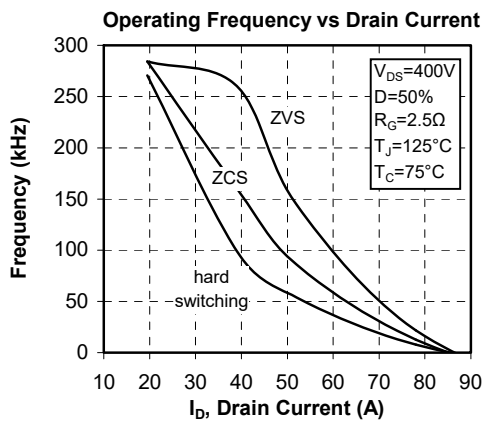
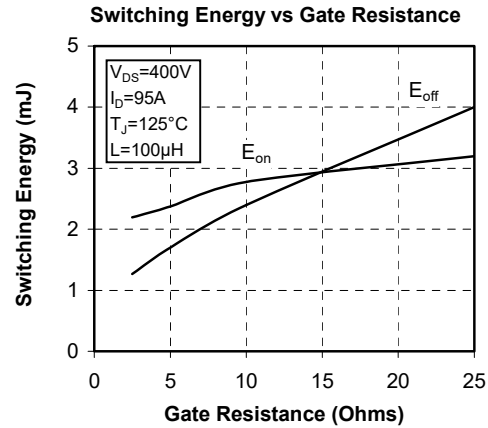
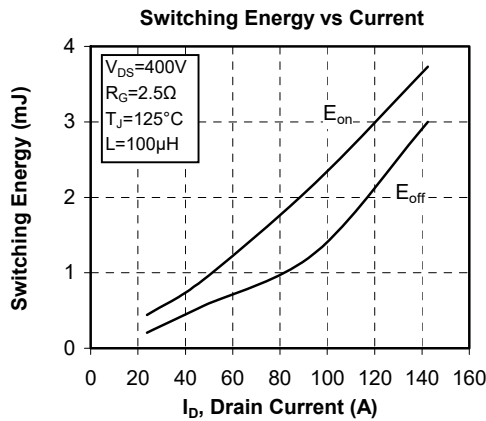
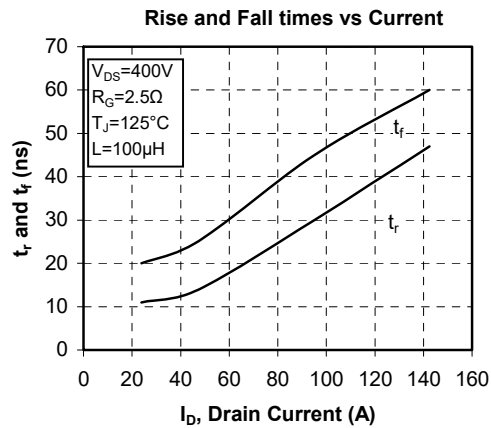
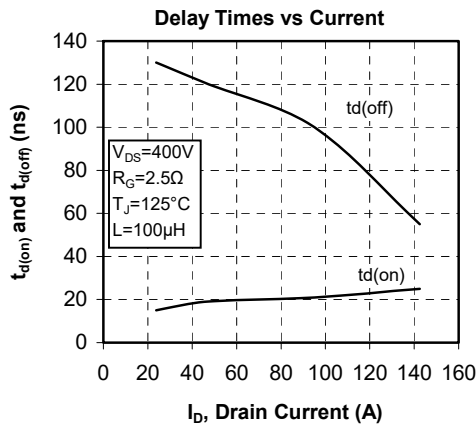


See application note 1906 - Mounting Instructions for SP3F Power Modules on www.microsemi.com

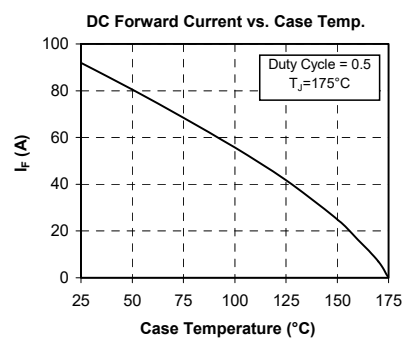
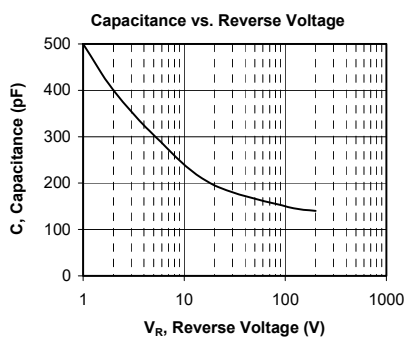
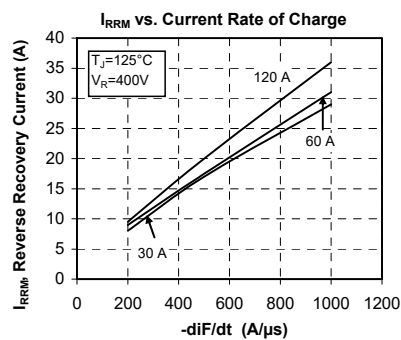
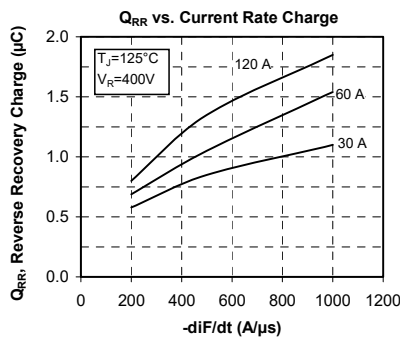
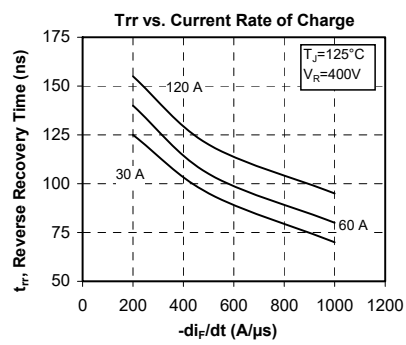
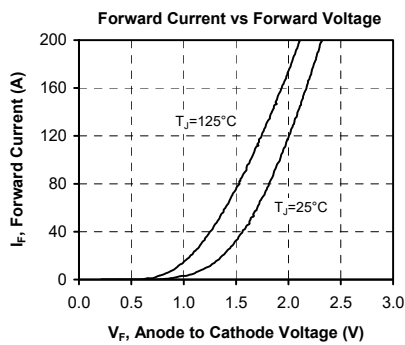
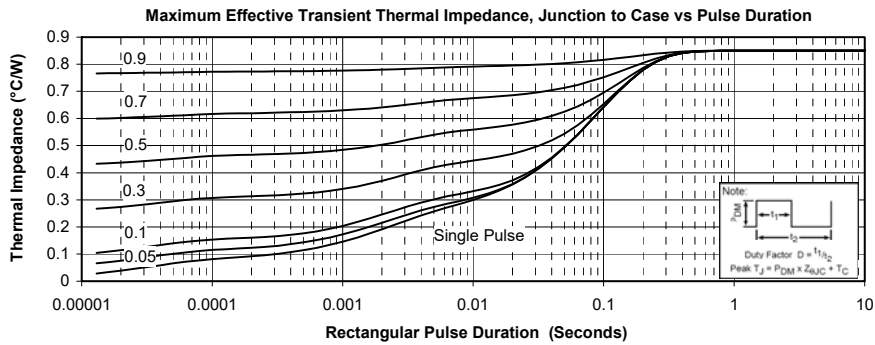
Typical Super junction MOSFET Performance Curve







Typical diode Performance Curve



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[80EH1](#) [MT9HVF6472PZ-667G1](#) [ND104N16K](#) [25.163.0653.1](#) [25.163.2453.0](#) [25.163.4253.0](#) [25.190.2053.0](#) [25.194.3453.0](#) [25.320.4853.1](#)
[25.320.5253.1](#) [25.325.3653.1](#) [25.326.3253.1](#) [25.326.3553.1](#) [25.330.1653.1](#) [25.330.4753.1](#) [25.330.5253.1](#) [25.334.3253.1](#)